



Material Content Data Sheet



Sales Product Name		BSC067N06LS3 G		Issued		1. August 2018		
MA#		MA001624888						
Package		PG-TDSON-8-40		Weight*		112.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.817	1.62	1.62	16176	16176
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		130	
	non noble metal	iron	7439-89-6	0.049	0.04		434	
	non noble metal	copper	7440-50-8	48.649	43.32	43.37	433009	433573
	non noble metal	copper	7440-50-8	0.060	0.05	0.05	535	535
wire	non noble metal	copper	7440-50-8	0.060	0.05	0.05	535	535
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		736	
	plastics	epoxy resin	-	6.529	5.81		58112	
	inorganic material	silicondioxide	60676-86-0	34.711	30.90	36.78	308950	367798
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13529	13529
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1410	1410
solder	non noble metal	tin	7440-31-5	0.037	0.03		325	
	noble metal	silver	7440-22-4	0.046	0.04		407	
	non noble metal	lead	7439-92-1	1.746	1.55	1.62	15541	16273
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.910	15.05	15.07	150510	150706
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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